

# SPECIFICATION FOR APPROVAL

CUSTOMER : \_\_\_\_\_

PRODUCT TYPE : SMD GLASS SEALING X'TAL 3.2\*2.5

NOMINAL FREQ. : 12.288000MHz

TXC P/N : AV12200001

REVISION : A1

CUSTOMER P/N : \_\_\_\_\_

PM / SALES : \_\_\_\_\_

DATE : \_\_\_\_\_

CUSTOMER SIGNATURE & Date

\_\_\_\_\_

\_\_\_\_\_

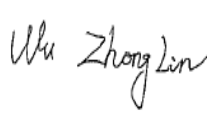
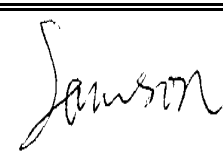

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

**MSL:Level 1  
RoHS Compliant**

Pb used in sealing glass material is exempt from EU directive

# PRODUCT SPECIFICATION SHEET

PRODUCT TYPE : SMD GLASS SEALING X'TAL 3.2\*2.5  
NOMINAL FREQ. : 12.288000MHz  
TXC P/N : AV12200001  
REVISION : A1

PE/RD	QA	MFG
		
7-Sep-11	7-Sep-11	7-Sep-11

NOTE:

- (1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required

**MSL:Level 1**  
**RoHS Compliant**

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## Spec Sheet Contents

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## ■ ELECTRICAL SPECIFICATIONS

### Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : 25±5°C

Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature : 25±3°C

Relative humidity : 40%~70%

### Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

### Crystal cutting type

The crystal is using AT CUT (thickness shear mode).

### Unit Weight:

0.018±0.001 g/pcs

	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYP	MAX	UNITS	
1	Nominal Frequency	FL	12.288000			MHz	-
2	Oscillation Mode	-	Fundamental			-	-
3	Load Capacitance	CL	18			pF	-
4	Frequency Tolerance	-	±20			ppm	at 25 °C ± 3 °C
5	Frequency Stability	-	±30			ppm	Over Operating Temp. Range (Reference 25°C)
6	Operating Temperature	-	-40	~	85	°C	-
7	Aging	-	±3			ppm	1st Year
8	Drive Level	DL	-	50	-	uW	-
9	Series Resonant Resistance	Rr	-	-	150	Ω	-
10	Shunt Capacitance	C0	-	-	-	pF	-
11	Insulation Resistance	-	500	-	-	MΩ	at DC 100V
12	Storage Temperature Range	-	-40	~	85	°C	-

## ■ FACTORY LOCATION

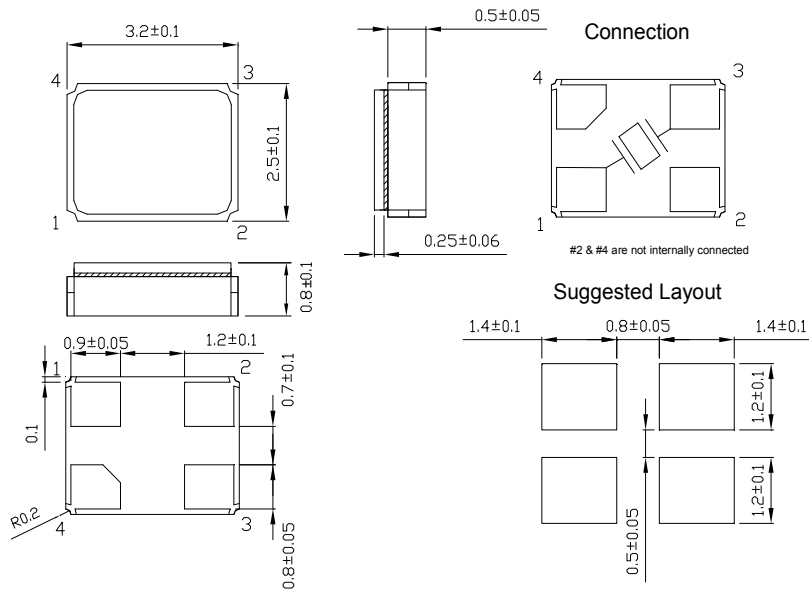
TXC (NINGBO) CORPORATION

NO.189 Huang Shan West Road, Beilun District,

Ningbo Zhejiang China

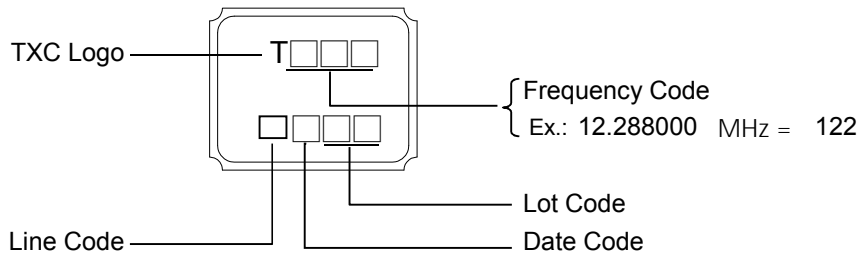
**■ DIMENSIONS**

(Unit:mm)



\*Coplanarity of solderable areas Camber 0.10 mm Max

**■ MARKING**



**Date Code:**

YEAR \ MONTH				MONTH											
				JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
2005	2009	2013	2017	A	B	C	D	E	F	G	H	J	K	L	M
2006	2010	2014	2018	N	P	Q	R	S	T	U	V	W	X	Y	Z
2007	2011	2015	2019	a	b	c	d	e	f	g	h	j	k	l	m
2008	2012	2016	2020	n	p	q	r	s	t	u	v	w	x	y	z

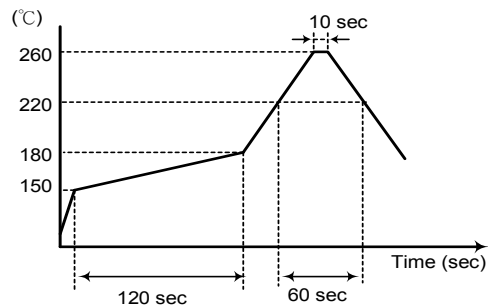
\*This date code will be cycled every four years

**■ SUGGESTED REFLOW PROFILE**

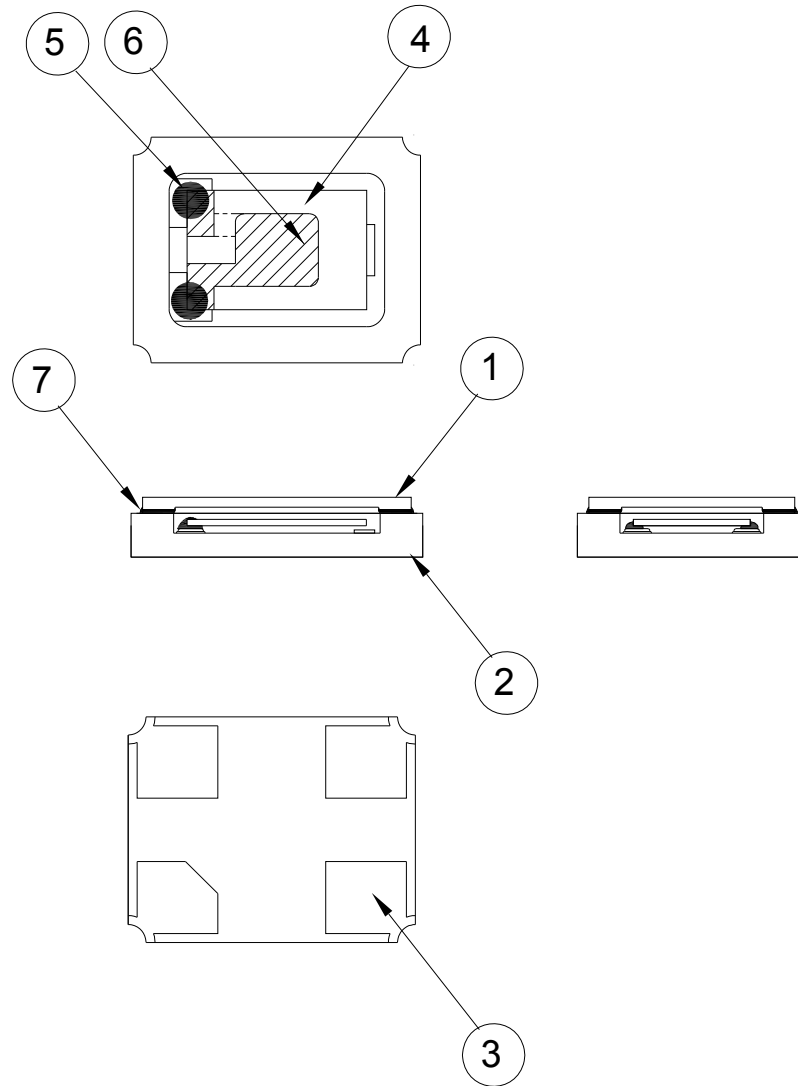
Solder melting point :  $220 \pm 10$  °C, 60 sec. Min.  
 Peak Temperature:  $260 \pm 5$  °C, 10 sec. Max.

**■ SUGGESTED MANUAL SOLDER CONDITION**

Temperature:  $350 \pm 10$  °C  
 Time: 3 sec.  
 Re-solder times: twice

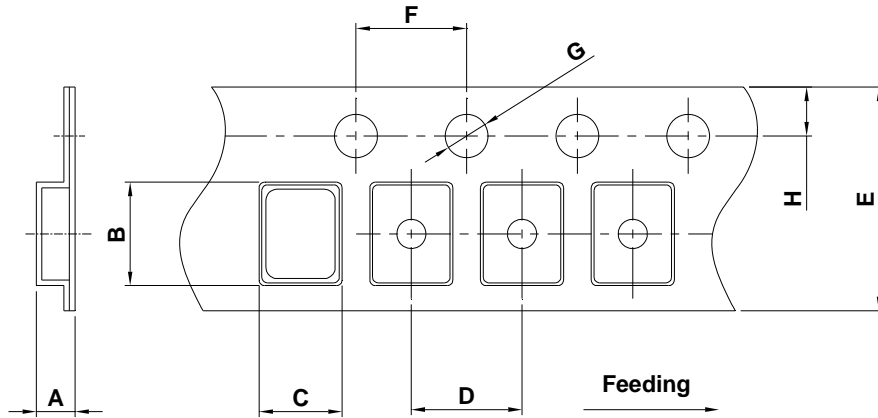


■ STRUCTURE ILLUSTRATION



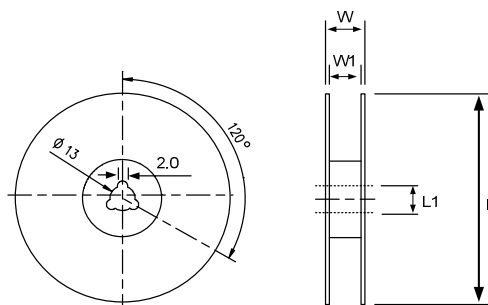
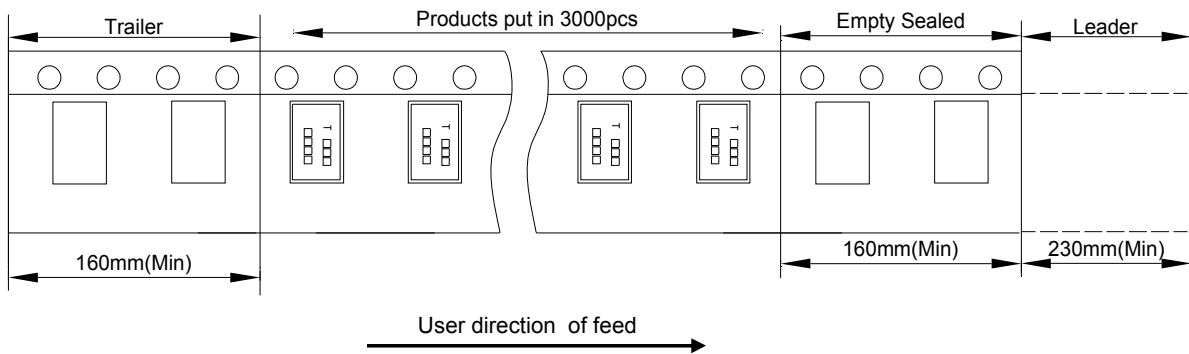
NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Cap	Ceramic (Al <sub>2</sub> O <sub>3</sub> )	-
2	Package	Ceramic (Al <sub>2</sub> O <sub>3</sub> )	-
3	PAD	Au	Tungsten metalize + Ni plating + Au plating
4	Crystal blank	SiO <sub>2</sub>	-
5	Conductive adhesive	Resin+Ag	-
6	Electrode	Noble Metal	-
7	Sealing Glass	Glass(PbO)	-

■ EMOSS CARRIER TAPE & REEL



DIMENSIONS	A	B	C	D	E	F	G	H	(UNIT : mm)
	1.65±0.10	3.40±0.10	2.70±0.10	4.00±0.10	8.00±0.20	4.00±0.10	1.55±0.10	1.75±0.10	

REMARK :



DIMENSIONS	L	L1	W	W1	(UNIT : mm)
	178±1.00	13±0.50	11.5±0.20	8±0.10	



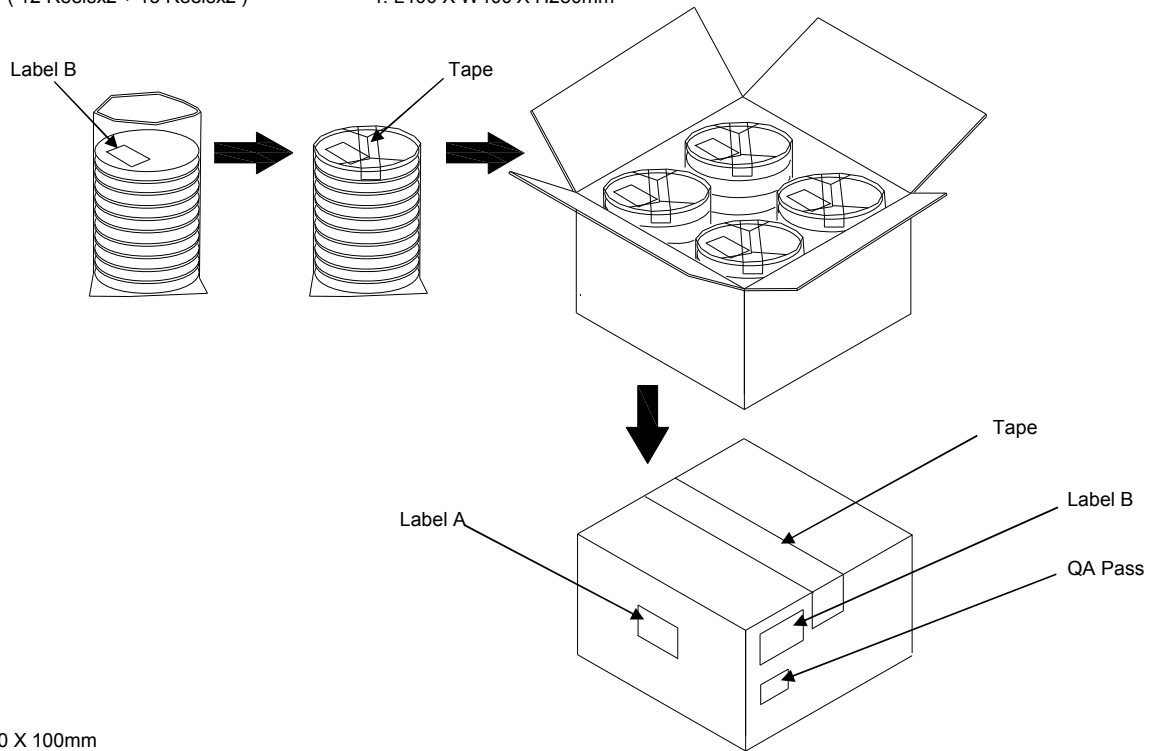
**PACKING**

Reel Quantity :

1. Reel X 6 (6 Reels)
2. Reel X 12 (12 Reels)
3. Reel X 25 (12 Reels + 13 Reels)
4. Reel X 50 (12 Reelsx2 + 13 Reelsx2)

Box Size:

1. L200 X W200 X H140mm
2. L200 X W200 X H250mm
3. L400 X W200 X H250mm
4. L400 X W400 X H280mm



(Label A) Size:100 X 100mm

<h1>TXC</h1>
Inv No: 00096815
Po No: 21106326- 24- 1
Part No: <span style="border: 1px solid black; padding: 2px;">                    </span>
Qty: 40000 PCS
C/No: 157- 44

(Label B) Size:80 X 40mm

TXC CORPORATION		QA PASS
DATE CODE: <span style="border: 1px solid black; padding: 2px;">                    </span>	QTY: <span style="border: 1px solid black; padding: 2px;">                    </span>	2011/09/02
LOT NO: <span style="border: 1px solid black; padding: 2px;">                    </span>	<b>RoHS</b>	
PART NO: <span style="border: 1px solid black; padding: 2px;">                    </span>	<b>HF</b>	
FREQ: <span style="border: 1px solid black; padding: 2px;">                    </span>		

**[STORAGE]**

- 1.The storage time to be 1 year maximum.
- 2.Don't be caught in the rain.
- 3.The storage environment shall be 5°C ~40°C temperature and 30% ~ 75%RH humidity and free from the sun shine.
- 4.If customers have special requirements, we can paste labels according to it.

**■ RELIABILITY SPECIFICATIONS**
**1.Mechanical Endurance**

No.	Test Item	Test Methods	Test Criteria
1.1	Mechanical Shock	2000 G , 0.3 m Sec. ,3 times for all 3 directions.	B C
1.2	Vibration	Frequency range                      10 ~ 2000 Hz Acceleration                              5G Sweep time                                20 minute Pendicular axes each test time        4 hours (Total test time 12 hours)	B C
1.3	Terminal Strength	17.7N force for 60sec +/-1sec.	F
1.4	Board Flex	Duration time:60 Sec Minimum,Deviation:3mm	B C

**2.Environmental Endurance**

No.	Test Item	Test Methods	SPEC
2.1	Solderability	Temperature                              245 °C +/- 5°C Immersing depth                          0.5 mm minimum Immersion time                            5 +/- 0.5 seconds Flux                                              Rosin resin methyl alcohol solvent ( 1 : 4 )	E
2.2	Resistance To Soldering Heat	Test temperature                          260 +/- 5 °C Test time                                      10 +/- 1 sec. Emersion Rate                              25 ± 6 mm/s Immersed of specimen                    1.5mm	BCD
2.3	High Temp. Storage	+ 85°C ± 3 °C for 1000 ± 12 Hrs	BCD
2.4	Low Temp. Storage	- 40 °C ± 3 °C for 1000 ± 12 Hrs	BCD
2.5	Thermal Shock	-40°C~85°C,for 1000 cycles. 	BCD
2.6	Operational Life	1000 hrs @ 85± 3°C. Rated VDD applied with 1 MΩ.	BCD
2.7	High Temp & Humidity	85°C ± 3°C , RH 85% , 1000 Hrs	BCD

**RELIABILITY SPECIFICATIONS**

Specifications	
A	Frequency change: Within $\pm 5$ ppm or in customer's specification.
B	Frequency change: Within $\pm 10$ ppm or in customer's specification.
C	Equivalent series resistance(E.S.R) change: Within $\pm 15\%$ or $10\Omega$ (larger value).
D	After conditioning , quartz crystal units shall be subjected to standard atmospheric conditions for 24 hour, and measured.
E	Minimum 95% of immersed terminal shall be covered with new uniform solder.
F	No damage on specimen

**Measurement condition**

Electrical characteristics measured by S&A250B or equivalent.